Claims

- 1 (currently amended): A low application temperature hot melt adhesive that is applied at or below 300°F and wherein the bonded adhesive heat stress value and the adhesive application temperature are separated by 110°F or less at temperature of below 250°F, has a viscosity between about 800 cps and 1500 cps at the adhesive application temperature, and wherein the bonded adhesive heat stress value and the adhesive application temperature are separated by 100°F or less.
- 2 (currently amended): The adhesive of claim 1 that is applied at or below 250°F and wherein the bonded adhesive heat stress value and the adhesive application temperature are separated by 100°F or less a temperature of about 200°F.
- 3 (currently amended): The adhesive of elaim 2 claim 1 that is applied at or below a temperature of 200°F and wherein the bonded adhesive heat stress value and the adhesive application temperature are separated by 100°F or less.
- 4 (previously amended): The adhesive of claim 1 wherein crystallization of the adhesive when analyzed by differential scanning calorimeter from application temperature to room temperature at a cooling rate of 150°C/min yields a time between initial cooling and crystallization of 0.35 minutes or greater.
- 5 (original): The adhesive of claim 1 that is thermally stable at application temperature for a period of one hundred hours as indicated by a viscosity change within plus/minus ten percent of the original application viscosity.
- 6 (original): The adhesive of claim 1 further comprising an energy absorbing ingredient.

7 (original): The adhesive of claim 1 further comprising a fragrance.
8 (original): An article of manufacture comprising the adhesive of claim 1.
9 (canceled)
10 (original): The article of claim 8 which is a carton, case, tray, bag or book.
11 (canceled)
12 (original): A packaged article contained within a carton, case, tray or bag, wherein the carton, case, tray or bag comprises the adhesive of claim 1.
13 (original): The packaged article of claim 12 which is a packaged food article.
14-21 (canceled)
22 (previously presented): The adhesive of claim 3 wherein the bonded adhesive heat stress value and the adhesive application temperature are separated by 90°F or less.
23 canceled.
24 canceled.
25 (previously presented): The adhesive of claim 1 comprising an ethylene n-butyl acrylate copolymer.
26 (currently amended): A low application temperature hot melt adhesive that is applied at a

temperature of or below 250°F, has a viscosity between about 800 cps and 1500 cps at the adhesive application temperature, in which the bonded adhesive heat stress value and the adhesive application temperature are separated by 100°F or less, in which the crystallization of the adhesive when analyzed by differential scanning calorimeter from application temperature to room temperature at a cooling rate of 150°C/min yields a time between initial cooling and crystallization of 0.35 minutes or greater, and is thermally stable at the application temperature for a period of one hundred hours as indicated by a viscosity change within plus/minus ten percent of the original application viscosity.

27 (previously presented): The adhesive of claim 1 which comprises 20 wt % of an ethylene n-butyl acrylate copolymer and 10 wt % of an ethylene vinyl acetate copolymer.

28 (new): The adhesive of claim 26 that is applied at a temperature of about 200°F.

29 (new): The adhesive of claim 26 that is applied at or below a temperature of 200°F.